

Material Content Data Sheet

RoHS

Sales Product Name	IPD079N06L3 G	**Issued**	17. February 2022
MA#	MA005698071		
Package	PG-TO252-3-311	**Weight***	314.56 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.67	0.67	6740	6740
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		456	
	non noble metal	copper	7440-50-8	143.098	45.49	45.55	454920	455513
wire	non noble metal	aluminium	7429-90-5	2.629	0.84	0.84	8359	8359
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.978	0.63		6289	
	plastics	brominated resin	-	2.119	0.67		6738	
	organic material	carbon black	1333-86-4	2.261	0.72		7187	
	plastics	epoxy resin	-	19.075	6.06		60642	
	inorganic material	silicondioxide	60676-86-0	115.865	36.83	44.91	368346	449202
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11890	11890
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
solder	non noble metal	tin	7440-31-5	0.044	0.01		139	
	noble metal	silver	7440-22-4	0.055	0.02		174	
	non noble metal	lead	7439-92-1	2.095	0.67	0.70	6661	6974
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.10	6.11	60967	61046
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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